

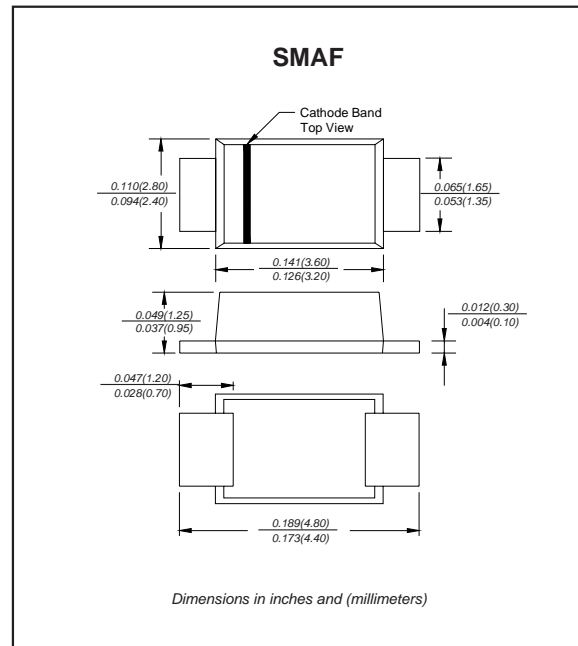
### Features

- ◆ The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- ◆ For surface mounted applications
- ◆ Low reverse leakage
- ◆ Built-in strain relief, ideal for automated placement
- ◆ High forward surge current capability
- ◆ High temperature soldering guaranteed: 250°C/10 seconds at terminals
- ◆ Glass passivated chip junction
- ◆ Compliant to RoHS Directive 2011/65/EU
- ◆ Compliant to Halogen-free

### Mechanical data

- ◆ **Case:** JEDEC SMAF molded plastic body
- ◆ **Terminals:** Solder plated, solderable per MIL-STD-750, Method 2026
- ◆ **Polarity:** Color band denotes cathode end
- ◆ **Mounting Position:** Any

### Package outline



### Maximum ratings and Electrical Characteristics (AT $T_A=25^\circ\text{C}$ unless otherwise noted)

PARAMETER	CONDITIONS	Symbol	MIN.	TYP.	MAX.	UNIT
Forward rectified current	See Fig. 1	$I_o$			1.0	A
Forward surge current	8.3ms single half sine-wave (JEDEC methode)	$I_{FSM}$			30	A
Reverse current	$V_R = V_{RRM}$ $T_A = 25^\circ\text{C}$	$I_R$			5.0	$\mu\text{A}$
	$V_R = V_{RRM}$ $T_A = 100^\circ\text{C}$				50	
Thermal resistance	Junction to ambient NOTE 1	$R_{\theta JA}$		55		$^\circ\text{C}/\text{W}$
Diode junction capacitance	f=1MHz and applied 4V DC reverse voltage	$C_J$		15		pF
Storage temperature		$T_{STG}$	-65		+150	$^\circ\text{C}$

**Note:** 1.P.C.B. mounted with 0.2x0.2" (5.0x5.0mm) copper pad areas

SYMBOLS	$V_{RRM}^{*1}$ (V)	$V_{RMS}^{*2}$ (V)	$V_R^{*3}$ (V)	$V_F^{*4}$ (V)	Operating temperature $T_J$ , ( $^\circ\text{C}$ )
S1A-F	50	35	50	1.10	-55 to +150
S1B-F	100	70	100		
S1D-F	200	140	200		
S1G-F	400	280	400		
S1J-F	600	420	600		
S1K-F	800	560	800		
S1M-F	1000	700	1000		

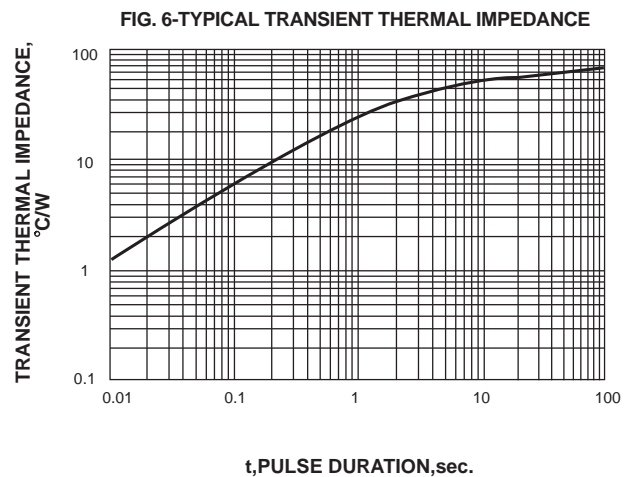
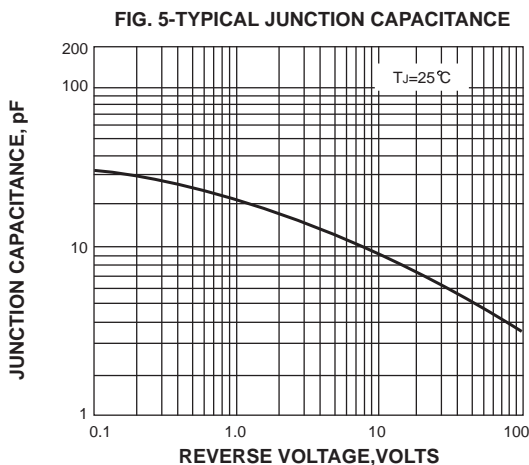
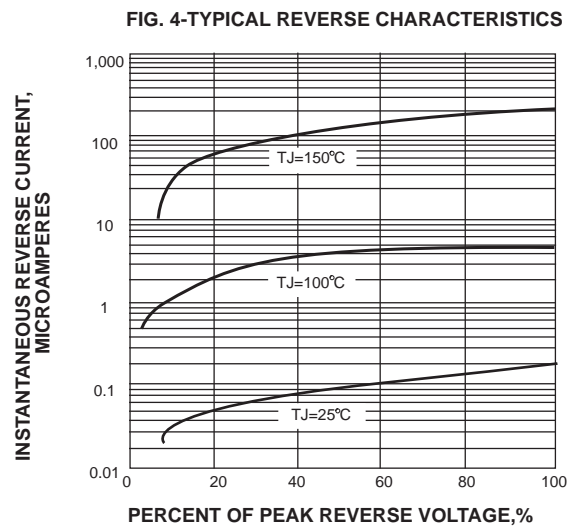
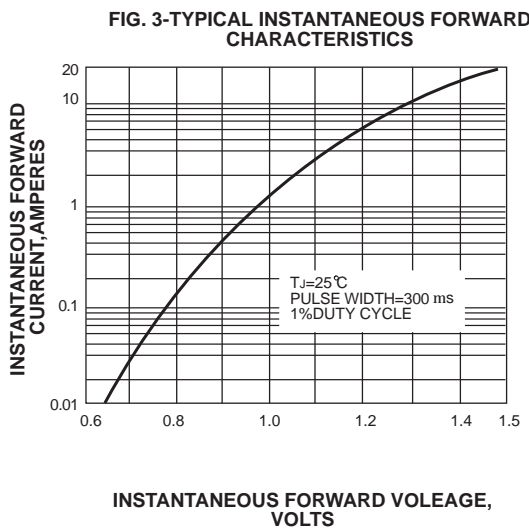
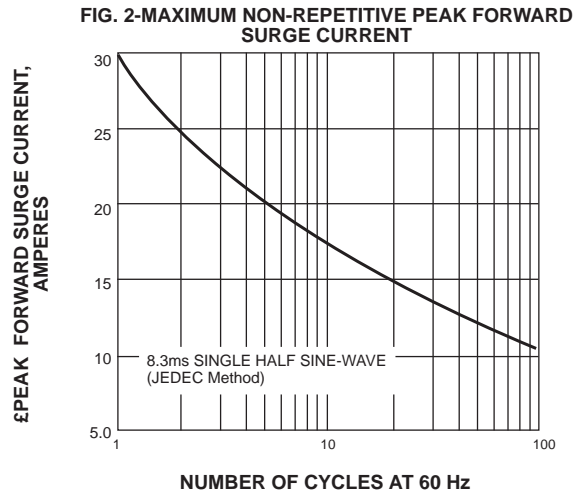
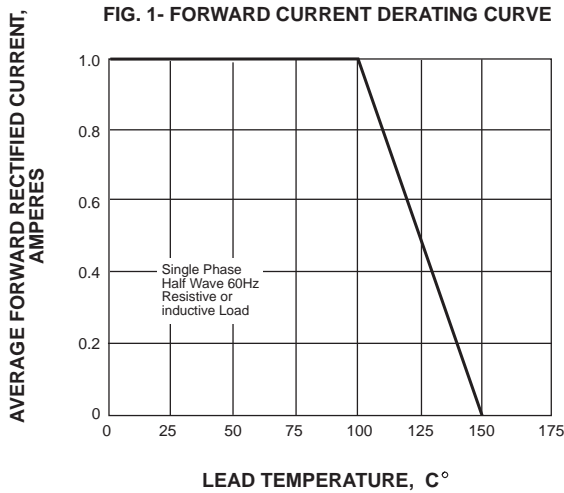
\*1 Repetitive peak reverse voltage

\*2 RMS voltage

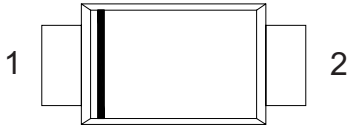

\*3 Continuous reverse voltage

\*4 Maximum forward voltage@ $I_F=1.0\text{A}$

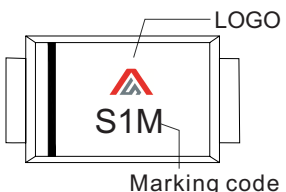
### Rating and characteristic curves



### Pinning information

Pin	Simplified outline	Symbol
Pin1 cathode Pin2 anode		

### Marking

Type number	Marking code	Example
S1A-F	S1A	
S1B-F	S1B	
S1D-F	S1D	
S1G-F	S1G	
S1J-F	S1J	
S1K-F	S1K	
S1M-F	S1M	

### Suggested solder pad layout



Dimensions in inches and (millimeters)

PACKAGE	A	B	C
SMAF	0.110 (2.80)	0.063 (1.60)	0.087 (2.20)